## Device Material Content

### Package: 256 caBGA

**Total Device Weight**: 0.520 Grams

### Package Code: LCMXO3ID

### Products:

- **Size (mm)**: 14 x 14
- **Lead pitch (mm)**: 0.8
- **MSL**: 3
- **Reflow max (°C)**: 260

### Notes / Assumptions:

- Die size: 5.23 x 6.26 x 0.279 mm
- Die attach epoxy: Henkel QMI-529HT

### % of Total Pkg. Wt. | Weight (g) | Notes / Assumptions
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Die | 4.09% | Silicon chip, 7440-21-3, 100.00%
Mold Compound | 49.24% | Epoxy Resin A, 7440-50-8, 97.05%
| | Epoxy Resin B, 7440-22-4, 85.00%
| | Phentol Resin, 7440-50-8, 3.00%
| | Silica, vitreous, 60676-86-0, 72.50%
| | Silicon dioxide, 7631-86-9, 15.00%
| | Aluminium and its compounds, - , 3.00%
| | Carbon Black, 1333-86-4, 0.50%
D/A Epoxy | 0.69% | Silver, 7440-22-4, 85.00%
| | Isobornyl Methacrylate, 7534-94-3, 10.00%
| | Epoxy Resin A - 3.00%, 7440-50-8, 97.05%
| | Epoxy Resin B - 3.00%, 7440-22-4, 85.00%
| | Phenol Resin - 3.00%, 7440-50-8, 3.00%
Wire | 0.36% | Copper (Cu), 7440-50-8, 96.50%
| | Palladium (Pd), 7440-22-4, 3.00%
| | Gold (Au), 7440-50-8, 0.50%
Solder Balls | 17.39% | Tin (Sn), 7440-31-5, 96.50%
| | Silver (Ag), 7440-22-4, 3.00%
| | Copper (Cu), 7440-50-8, 0.50%
Substrate | 15.07% | Glass fiber, 65997-17-3, 45.00%
| | BT Resins, 21645-51-2, 27.50%
Solder mask | 2.09% | Glass fiber, 65997-17-3, 45.00%
| | Inorganic filler, 21645-51-2, 27.50%
Foil | 11.08% | Copper, 7440-50-8, 93.17%
| | Nickel plating, 7440-02-0, 5.62%
| | Gold plating, 7440-57-5, 1.21%

### Notes:

- The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.
- Constituent substances and proportions in epoxy materials are before curing.
- The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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